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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Charles W.C. Lin
Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA
Serial No.: 09/852,824 Filed: May 10, 2001
Examiner: Graybill, D. Group Art Unit: 2827
Atty. Docket No.: P002-2

COMMISSIONER FOR PATENTS
P.O. Box 1450
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RESPONSE

In response to the Office Action dated September 23, 2004, please amend the application as follows.

The Claim Amendments begin at page 2.

The Remarks begin at page 17.